10/002,925

L Number	Hits	Search Text	DB	Time stamp
1	838	(stack\$3 near3 (chip die dice wafer semiconductor IC (integrated adj	USPAT;	2004/02/18 10:44
		circuit))) and @ad<19990503 and shield\$3	US-PGPUB;	
			ЕРО; ЛРО;	
			DERWENT;	
			IBM_TDB	
2	97	(stack\$3 near3 (chip die dice wafer semiconductor IC (integrated adj	USPAT;	2004/02/18 10:45
	- '	circuit))) and @ad<19990503 and (shield\$3 near4 (wall side outside	US-PGPUB;	
		exterior))	EPO, JPO;	
			DERWENT;	
			IBM_TDB	
_	174	harazny nama va	USPAT;	2004/02/18 09:53
•	174	berezny-nema.xa.		2004/02/16 07.55
			US-PGPUB; EPO; JPO;	
			DERWENT;	
			IBM_TDB	2004/02/25 22 22
-	0	berezny-nema.xa.	US-PGPUB	2004/02/17 11:02
-	141078	transmit\$4 and receiv\$3 and @ad<19990503 and (semiconductor die	USPAT;	2004/02/17 11:49
		dice chip IC (integrated adj circuit))	US-PGPUB;	
			ЕРО; ЛРО;	
			DERWENT;	
		·	IBM_TDB	
_	317	(transmit\$4 and receiv\$3 and @ad<19990503 and (semiconductor die	USPAT;	2004/02/17 11:51
	51.	dice chip IC (integrated adj circuit))) and (chip near3 stack\$3)	US-PGPUB;	
		and the to (magness and anomal)) and (anth month amount)	ЕРО; ЛРО;	
			DERWENT;	
			IBM_TDB	
		(() () () () () () () () () () () () ()		2004/02/17 12:21
-	14	((transmit\$4 and receiv\$3 and @ad<19990503 and (semiconductor die	USPAT;	2004/02/17 12:21
		dice chip IC (integrated adj circuit))) and (chip near3 stack\$3)) and	US-PGPUB;	
		deactivat\$3	EPO; JPO;	
			DERWENT;	
		·	IBM_TDB	
-	4	(("5444387") or ("5229647")).PN.	USPAT;	2004/02/17 14:48
			US-PGPUB;	
			ЕРО; ЛРО;	
			DERWENT;	
			IBM_TDB	
-	0	tranceiver and @ad<19990503 and (stack\$3 near3 (semiconductor die	USPAT;	2004/02/17 14:54
	J	dice chip IC (integrated adj circuit) wafer))	US-PGPUB;	
		area omp to (miogration and onemic) water))	ЕРО; ЛРО;	
			DERWENT;	
		•		
	**00	· · · · · · · · · · · · · · · · · · ·	IBM_TDB	2004/02/17 14:5:
-	1190	transmit\$4 and receiv\$3 and @ad<19990503 and (stack\$3 near3	USPAT;	2004/02/17 14:54
		(semiconductor die dice chip IC (integrated adj circuit) wafer))	US-PGPUB;	
			ЕРО; ЛРО;	
			DERWENT;	
			IBM_TDB	
-	486	(transmit\$4 and receiv\$3 and @ad<19990503 and (stack\$3 near3	USPAT;	2004/02/17 14:5:
		(semiconductor die dice chip IC (integrated adj circuit) wafer))) and	US-PGPUB;	1
		interconnect\$3	ЕРО; ЛРО;	
	•		DERWENT;	1
			IBM_TDB	
-	177	((transmit\$4 and receiv\$3 and @ad<19990503 and (stack\$3 near3	USPAT;	2004/02/17 15:01
	17		US-PGPUB;	200 1/02/17 15.0
		(semiconductor die dice chip IC (integrated adj circuit) wafer))) and		
		interconnect\$3) and deactivat\$3	ЕРО; ЛРО;	
			DERWENT;	
-			IBM_TDB	
	316	((transmit\$4 and receiv\$3 and @ad<19990503 and (stack\$3 near3	USPAT;	2004/02/17 17:14
		(semiconductor die dice chip IC (integrated adj circuit) wafer))) and	US-PGPUB;	
		interconnect\$3) and (test\$3 fail\$3 bad malfunction\$3)	ЕРО; ЛРО;	
		,	DERWENT;	
		1	,	

-	1572	((438/109) or (257/777)).CCLS.	USPAT,	2004/02/17 17:14
			US-PGPUB;	
			ЕРО; ЛРО;	
			DERWENT;	
			IBM_TDB	
-	762	(((438/109) or (257/777)).CCLS.) and @ad<19990503	USPAT,	2004/02/17 17:15
			US-PGPUB;	
		•	ЕРО; ЈРО;	
	1		DERWENT;	
			IBM_TDB	
-	83	(((((438/109) or (257/777)).CCLS.) and @ad<19990503) and (shield\$3	USPAT;	2004/02/17 17:15
		emf emi interference)	US-PGPUB;	
			ЕРО; ЈРО;	
	1		DERWENT;	
			IBM_TDB	